

LINEAR SYSTEMS

Twenty-Five Years Of Quality Through Innovation

FEATURES

VERY HIGH INPUT IMPEDANCE

HIGH GATE BREAKDOWN

ULTRA LOW LEAKAGE

LOW CAPACITANCE

ABSOLUTE MAXIMUM RATINGS (NOTE 1)

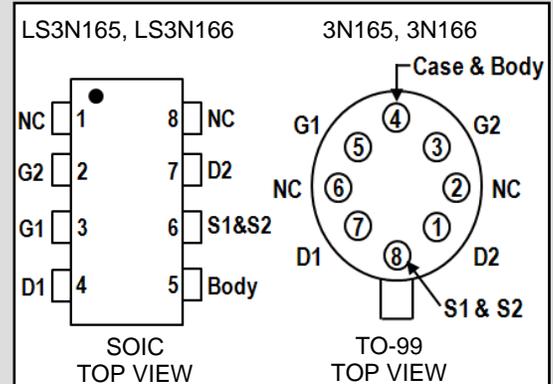
($T_A=25^\circ\text{C}$ unless otherwise noted)

Drain-Source or Drain-Gate Voltage (NOTE 2)

3N165	40 V
3N166	30 V
Gate-Gate Voltage	± 80 V
Drain Current (NOTE 2)	50 mA
Storage Temperature	-55°C to $+150^\circ\text{C}$
Operating Temperature	-55°C to $+150^\circ\text{C}$
Lead Temperature (Soldering, 10 sec.)	$+300^\circ\text{C}$
Power Dissipation (One Side)	300 mW
Total Derating above 25°C	4.2 mW/ $^\circ\text{C}$

LS/3N165, LS/3N166

MONOLITHIC DUAL P-CHANNEL
ENHANCEMENT MODE MOSFET

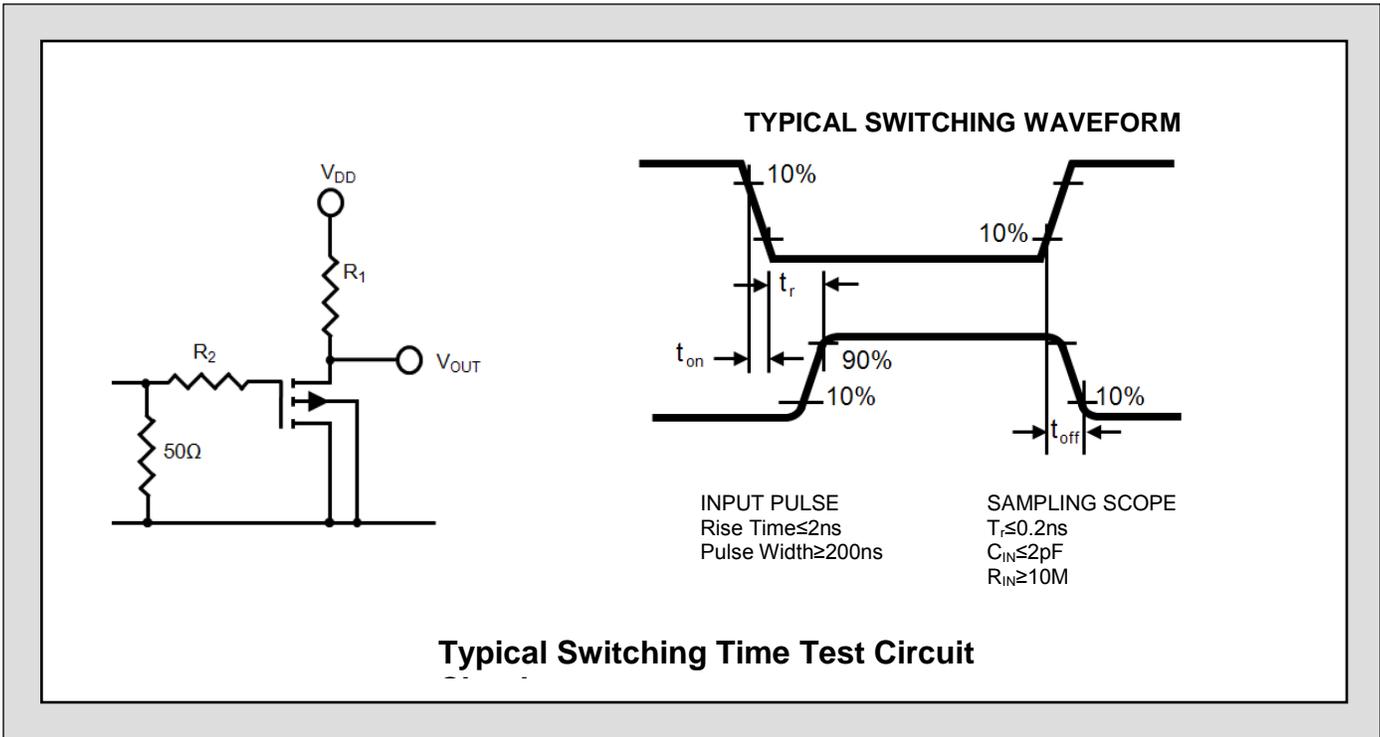


ELECTRICAL CHARACTERISTICS ($T_A=25^\circ\text{C}$ and $V_{BS}=0$ unless otherwise noted)

SYMBOL	CHARACTERISTIC	3N165 & 3N166		LS3N165 & LS3N166		UNITS	CONDITIONS
		MIN	MAX	MIN	MAX		
I_{GSSR}	Gate Reverse Leakage Current	--	10	--	100	pA	$V_{GS}=40\text{V}$
I_{GSSF}	Gate Forward Leakage Current	--	-10	--	-100		$V_{GS}=-40\text{V}$
I_{DSS}	Drain to Source Leakage Current	--	-200	--	-200		$T_A=+125^\circ\text{C}$
I_{SDS}	Source to Drain Leakage Current	--	-400	--	-400		$V_{DS}=-20\text{V}, V_{GS}=V_{BS}=0\text{V}$
$I_{D(on)}$	On Drain Current	-5	-30	-5	-30	mA	$V_{SD}=-20\text{V}, V_{GD}=V_{DB}=0\text{V}$
$V_{GS(th)}$	Gate Source Threshold Voltage	-2	-5	-2	-5		$V_{DS}=-15\text{V}, I_D=-10\mu\text{A}, V_{SB}=0\text{V}$
$V_{GS(th)}$	Gate Source Threshold Voltage	-2	-5	-2	-5	V	$V_{DS}=V_{GS}, I_D=-10\mu\text{A}, V_{SB}=0\text{V}$
$r_{DS(on)}$	Drain Source ON Resistance	--	300	--	300		ohms
g_{fs}	Forward Transconductance	1500	3000	1500	3000	μS	$V_{DS}=-15\text{V}, I_D=-10\text{mA}, f=1\text{kHz}$
g_{os}	Output Admittance	--	300	--	300		$V_{SB}=0\text{V}$
C_{iss}	Input Capacitance	--	3.0	--	3.0	pF	$V_{DS}=-15\text{V}, I_D=-10\text{mA}, f=1\text{MHz}$ (NOTE 3) $V_{SB}=0\text{V}$
C_{rss}	Reverse Transfer Capacitance	--	0.7	--	1.0		
C_{oss}	Output Capacitance	--	3.0	--	3.0		
$R_E(Y_{is})$	Common Source Forward Transconductance	1200	--			μS	$V_{DS}=-15\text{V}, I_D=-10\text{mA}, f=100\text{MHz}$ (NOTE 3) $V_{SB}=0\text{V}$

MATCHING CHARACTERISTICS 3N165

SYMBOL	CHARACTERISTIC	LIMITS		UNITS	CONDITIONS
		MIN.	MAX.		
G_{fs1}/G_{fs2}	Forward Transconductance Ratio	0.90	1.0		$V_{DS}=-15V$ $I_D=-500\mu A$ $f=1kHz$ $V_{SB}=0V$
V_{GS1-2}	Gate Source Threshold Voltage Differential	--	100	mV	$V_{DS}=-15V$ $I_D=-500\mu A$ $V_{SB}=0V$
$\Delta V_{GS1-2}/\Delta T$	Gate Source Threshold Voltage Differential Change with Temperature	--	100	$\mu V/^\circ C$	$V_{DS}=-15V$ $I_D=-500\mu A$ $V_{SB}=0V$ $T_A=-55^\circ C$ to $+125^\circ C$



NOTES:

1. MOS field effect transistors have extremely high input resistance and can be damaged by the accumulation of excess static charge. To avoid possible damage to the device while wiring, testing, or in actual operation, follow these procedures:
To avoid the build-up of static charge, the leads of the devices should remain shorted together with a metal ring except when being tested or used. Avoid unnecessary handling. Pick up devices by the case instead of the leads. Do not insert or remove devices from circuits with the power on, as transient voltages may cause permanent damage to the devices.
2. Per transistor.
3. For design reference only, not 100% tested.

Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions above those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Linear Integrated Systems (LIS) is a 25-year-old, third-generation precision semiconductor company providing high-quality discrete components. Expertise brought to LIS is based on processes and products developed at Amelco, Union Carbide, Intersil and Micro Power Systems by company President John H. Hall. Hall, a protégé of Silicon Valley legend Dr. Jean Hoerni, was the director of IC Development at Union Carbide, co-founder and vice president of R&D at Intersil, and founder/president of Micro Power Systems.